



6th International IEEE Conference on Polymers and Adhesives in Microelectronics and Photonics

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IEEE Polytronic 2007 6th International IEEE Conference on Polymers and Adhesives in Microelectronics and Photonics

National Museum of Emerging Science and Innovation (Miraikan)
Odaiba, Tokyo, Japan
January 16-18, 2007

<http://www.polytronic.jp/>
info@polytronic.jp

Photo album



Conference at the Miraikan Hall of National Museum of Emerging Science and Innovation.



Conference reception, Jan. 16.



Coffee break & poster session



Social event, Jan. 17.



Best paper award of Polytronic 2007

Polytronic 2007, the 6th International IEEE Conference on Polymers and Adhesives in Microelectronics and Photonics, held on January 16-18, 2007, at National Museum of Emerging Science and Innovation in Tokyo, Japan, ended successfully. The lively interest in the cross-functional field of electronic packaging and active contributions of the researchers and engineers have sustained this symposium ever since 2001 as an amalgamation of the previously successful series of IEEE Conferences on adhesives and polymers: Polymeric Materials for Microelectronic & Photonic Applications (POLY), Adhesives in Electronics, and Polymeric Electronics Packaging (PEP). It was in 6th session and the first time to be held in Japan, witnessing the growing interest in polymer applications in electronics, such as organic semiconductors with potential for large-area electronics manufacturing, inkjet technologies for on-demand fine pitch printing process, nanoscale device manufacturing, optical wiring technologies, polymer cells, and so on.

129 participants including 29 from overseas (USA, Germany, Poland, Hungary, Austria, France, Italy, England, Belgium, Korea, HongKong, Taiwan) attended the conference. 66 technical papers including 24 from overseas were presented. During the conference, two short course lectures as tutorial were delivered for the registrants: '3D integration technologies' given by Dr. Rajen Chanchani on January 15. and 'Accelerated Life Testing (ALT) in Micro-, Opto-electronics, and Photonics' given by Dr. Ephraim Suhir on January 16.

I believe that Polytronic 2007 has provided a unique opportunity for participants to deepen their knowledge of state-of-the-art polymers, adhesives, and packaging, on both applications and materials such as inks, electrical insulation interlayer materials and adhesives.

I would like to express my gratitude to the members of the Organizing Committee who have all worked so hard to ensure the conference is a resounding success. We would like also to acknowledge The IEEE CPMT Society for providing the organizational support in coordinating this symposium. We thank also Institute for Advanced Micro-system Integration (IMSI) for co-sponsoring and Japan Institute for Electronic Packaging (JIEP) for cooperation in conducting this symposium. Special thanks are due to the companies and organizations for sponsoring the conference. Finally I express my appreciation and thank all authors for presenting their latest research results, and all participants for their active cooperation.

Tokyo, January 18, 2007
Tadatomo Suga, Organizing Committee General Chair

Best Paper Award

The organizing committee selected the following three papers to be awarded the Best Paper of Polytronic2007, and the speakers of the presentations have received the certificate.

- Fast Response Blue and Green Organic LightSources with Different Fluorescence Lifetime Materials for the Wavelength Division Multiplexing Optical Interconnect Application: Takeshi Fukuda (Fujikura Ltd.), Tomoko Okada, Bin Wei, Musubu Ichikawa (Shinshu Univ.), Masakazu Ohashi (Fujikura Ltd.), Yoshio Taniguchi (Shinshu Univ.)

- ACF (Anisotropic Conductive Film) Batch Bonding Connection Changing Flip Chip BondingTechnology: Tatsuo Nagamatsu, Yuuji Kakiuchi, Yasuhiro Suga (Sony Chemical & Information Device Corp.)

- Elastic and Conformable Electronic Circuitsies Using MID in Polymer: Fabrice Axisa, D. Brosteaux, E. De Leersnyder, F. Bossuyt, M. Gonzalez, M. Vanden Bulcke, J. Vanfleteren (IMEC Belgium)

[Final program\(pdf\)](#)
[Tutorial](#)

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[Conference Report in Japanese](#)

Polytronic confereces:

- Polytronic 2001, Potsdam, Germany
- Polytronic 2002, Zalaegerszeg, Hungary
- Polytronic 2003, Montreux, Switzerland
- Polytronic 2004, Portland, USA
- Polytronic 2005, Wroclaw, Poland
- Polytronic 2007, Tokyo, Japan
- Polytronic 2008, USA



Proceedings of Polytronic 2007



webmaster@polytronic.jp